

IN THE CLAIMS:

Please amend the claims as follows:

Claim 1 (Previously Presented): An embedding resin for embedding an electronic part in an insulating substrate, assuming a color having a base color tone selected from among black, blue, green, red, orange, yellow, and violet, and comprising a thermosetting resin and at least one inorganic filler,

wherein the at least one inorganic filler has a particle size range of about 0.1 μm to 50 μm .

Claim 2 (Cancelled).

Claim 3 (Previously Presented): The embedding resin according to claim 1, wherein the thermosetting resin is at least one species selected from among a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, and a cresol-novolak-type epoxy resin.

Claim 4 (Original): The embedding resin according to claim 3, further comprising at least one coloring agent selected from among carbon black, a phthalocyanine-based pigment, an azo pigment, a quinoline-based pigment, an anthraquinone-based pigment, a triphenylmethane-based pigment, and an inorganic oxide.

Claim 5 (Cancelled).

Claim 6 (Original): The embedding resin according to claim 1, further comprising at least one coloring agent selected from among carbon black, a phthalocyanine-based pigment, an azo pigment, a quinoline-based pigment, an anthraquinone-based pigment, a triphenylmethane-based pigment, and an inorganic oxide.

Claim 7 (Previously Presented): The embedding resin according to claim 1, wherein the thermosetting resin contains a photosensitive resin.

Claim 8 (Previously Presented): The embedding resin according to claim 1, wherein the at least one inorganic filler is selected from among crystalline silica, fused silica, alumina, and silicon nitride.

Claim 9 (Previously Presented): The embedding resin according to claim 1, wherein the at least one inorganic filler is subjected to surface treatment by use of a coupling agent.

Claim 10 (Previously Presented): The embedding resin according to claim 4 wherein the amount of the coloring agent is 0.1-30 mass %.

Claim 11 (Previously Presented): The embedding resin according to claim 6 wherein the amount of the coloring agent is 0.1-30 mass %.

Claims 12-14 (Cancelled).

Claim 15 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

and at least one inorganic filler ~~The embedding resin according to claim 13,~~

wherein the at least one inorganic filler has a particle size range of about 0.1 μm to 50 μm .

Claim 16 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

at least one inorganic filler ~~The embedding resin according to claim 13,~~

wherein the thermosetting resin contains a photosensitive resin.

Claim 17 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

at least one inorganic filler ~~The embedding resin according to claim 13,~~

wherein the at least one inorganic filler is selected from among crystalline silica, fused silica, alumina, and silicon nitride.

Claim 18 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

at least one inorganic filler ~~The embedding resin according to claim 13,~~

wherein the at least one inorganic filler is subjected to surface treatment by use of a coupling agent.